

09-25-1998

FORM PTO-1595

(Rev. 6-93)

OMB No. 0651-0011 (exp. 4/94)



100837511

OVER SHEET  
LY

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks and the attached original documents or copy thereof.

9-1A-98

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1. Name of conveying part(ies):  
Chien-Li Kuo  
Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies)  
Name: United Microelectronics Corp.  
Street Address: No. 3, Li-Hsin Rd. II., Science-Based Industrial Park, Hsinchu City, Taiwan, R.O.C.  
Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance:  
 Assignment  Merger  
 Security Agreement  Change of Name  
 Other:  
Execution Date: August 12, 1998.

4. Application number(s) or patent number(s):  
If this document is being filed together with a new application, the execution date of the application is: August 20, 1998  
A. Patent application No.(s) B. Patent No.(s)  
Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:  
Daniel R. McClure  
Thomas, Kayden, Horstemeyer & Risley, L.L.P.  
100 Galleria Parkway, Suite 1500  
Atlanta, Georgia 30339

6. Total number of applications/patents involved: [ 1 ]

7. Total fee (37 CFR 3.41) \$ 40.00  
 Enclosed  
 Authorized to be charged to deposit account

8. Deposit Account Number:  
20-0778  
(Attach duplicate copy of this page if paying by Deposit Account)

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9. Statement and signature. *To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*  
Daniel R. McClure Date Sept 14, 1998  
Type Name of Person Signing - Daniel R. McClure  
Docket #: 252103-2290 Total number of pages including cover sheet, attachments, and document: [3]

Mail documents to be recorded with required cover sheet information to:  
Assistant Commissioner for Patents, Box Assignments  
Washington, D.C. 20231

AssignCoverSht.doc

09/24/1998 TTUN11 00000165 09152920

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# ASSIGNMENT

WHEREAS, Chien-Li Kuo

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: BONDING-PAD STRUCTURE FOR INTEGRATED CIRCUIT AND METHOD OF FABRICATING THE SAME

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp., of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

# ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Chion-li Kuo Aug. 12, 1998.  
Signature

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Signature

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Signature

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Signature